REMOVAL OF LOGIC CHIPS / DISCRETE COMPONENTS

(ALL FURTHER REFERENCES TO LOGIC CHIPS WILL PERTAIN EQUALLY TO ALL DISCRETE COMPONENTS. EXCEPTIONS WILL BE *NOTED*.)

STEP 1. APPLY LIBERAL AMOUNT OF FLUX TO AREA SURROUNDING LOGIC CHIP. USING THE SOLDER IRON SET TO 600 DEGREES, PLACE THE TIP AGAINST THE CHIP LEG, BUT OFF THE BARREL PAD, AND REMOVE SOLDER AS SOON AS IT FLOWS. CAUTION MUST BE EXERCISED IN THE LENGTH OF TIME THE IRON IS HEATING THE MODULE AS SERIOUS BOARD BURNS, PAD OR BARREL DAMAGE CAN OCCUR. USUALLY JUST A FEW SECONDS ARE REQUIRED TO FLOW THE SOLDER SUFFICIENTLY. IF HAVING PROBLEMS, FLOW THE SOLDER, LIFT THE LEG OUT AND REMOVE THE SOLDER FROM THE BARREL AFTER COMPLETING COMPONENT REMOVAL.

**** NOTE: AS ALWAYS, RESISTORS AND TRANSISTORS ARE THE HARDEST TO DESOLDER DUE TO HEAT DISSIPATION OR INACCESSABILITY OF THEIR LEGS WITH THE IRON. FLOWING THE SOLDER, REMOVING THE LEGS ONE AT A TIME AND THEN CLEANING UP THE BARRELS AFTER COMPONENT REMOVAL, IS STILL PROBABLY THE SAFEST ROUTE TO TAKE.